LCC48, 14.22x14.22
CASE 115AO
ISSUE A

DATE 31 JAN 2012
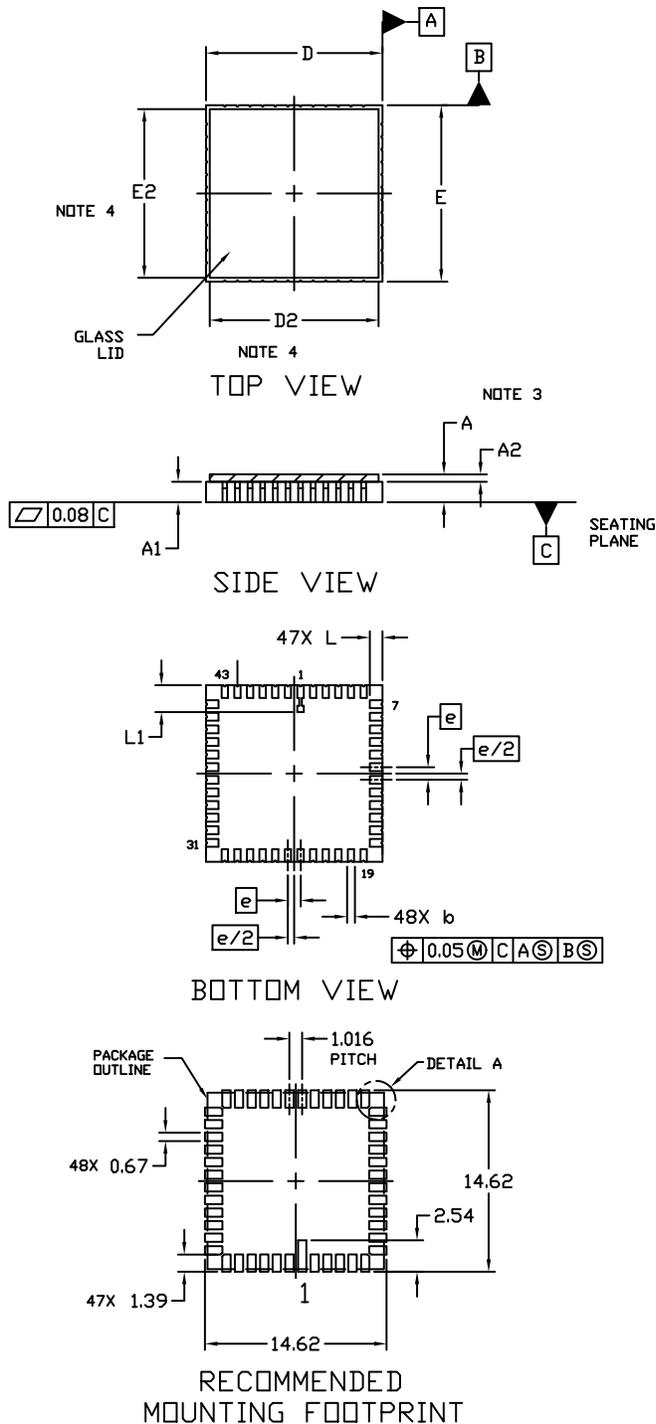
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.

TOP VIEW

SIDE VIEW

DETAIL A

BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT
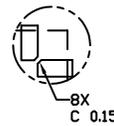
DIM	MILLIMETERS	
	MIN.	MAX.
A	1.85	2.55
A1	1.65 REF	
A2	0.55 REF	
b	0.43	0.59
D	14.09	14.35
D2	13.60 REF	
E	14.09	14.35
E2	13.60 REF	
e	1.016 BSC	
L	0.84	1.20
L1	1.90	2.42

GENERIC MARKING DIAGRAM
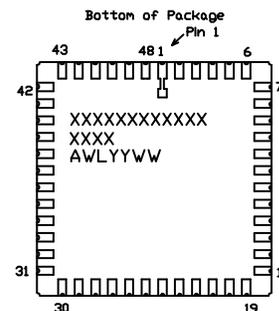
XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
NNNN = Serial Number

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